6398/DSM/BCVD

FORM PTO-1595
(Modified)

RECORDATION FORM COVER SHEET

PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

	EXECUTION DATE
Nagarajan Rajagopalan	July 8, 2002
Joe Feng	July 8, 2002
Christopher Ngai	July 8, 2002
Meiyee (Maggie Le) Shek	July 8, 2002
Suketu A Parikh	July 2, 2002
Linh H Thanh	July 3, 2002

Additional name(s) of conveying part(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Applied Materials, Inc.
Internal Address: Patent Department
Street Address: P. O. Box 450A
M/S #2061
City: Santa Clara State CA Zip 95054
Additional Name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
Other
Execution Date: SEE ABOVE

4. Application number(s) or patent Number(s):

If this document is being filed together with a new application, the execution date of the application is: _

A. Patent Application No.(s)

Serial No.:10/136,455 Filing Date:April 29, 2002

B. Patent No.(s)

Additional Numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: PATENT COUNSEL
Internal Address: Applied Materials, Inc.
Patent Dept.
Street Address: P. O. Box 450A
M/S 2061
City: Santa Clara State: CA ZIP: 95052

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)...........$40.00
☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number:
50-1074
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and any attached copy is a true copy of the original document.

Robert W. Mulcahy, Reg. No.25,436
Name of Person Signing

Signature

7/12/02
Date

10. Total number of pages comprising cover sheet, attachments, and document: 13

OMB No. 0651-0011 (exp. 4/94)

Mail documents to be recorded with the required cover sheet information to:
Commissioner of Patents & Trademarks , Box Assignments
Washington, D.C. 20231

Attorney Docket No.006398 / DSM/BCVD /JW

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

Nagarajan RAJAGOPALAN
1750 Halford Avenue
Apt. #101
Santa Clara, CA 95051

Joe FENG
10364 DEMPSTER AVENUE
CUPERTINO, CA 95014

Christopher S NGAI
2606 Summitt Drive
Burlingame, CA 94010

Meiyee (Maggie LE) SHEK
2351 Alvin Street
Mountain View, CA 94043

Suketu A PARIKH
4624 Aviara Court
San Jose, CA 95135

Linh H THANH
1084 Brookwell Drive
Cupertino, CA 95014

(hereinafter referred to as Assignors), have invented a certain invention entitled:

METHOD FOR FORMING SILICON CONTAINING LAYERS ON A SUBSTRATE

for which application for Letters Patent in the United States was filed on 04/29/2002, under Serial No. 10/136,455 , executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, Inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

Attorney Docket No.006398 / DSM/BCVD /JW

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue of extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperation with said Assignee to enable said Assignee to enjoy the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest here in conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions, provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

R. Nagarajan Date: 07/08/2002
Nagarajan RAJAGOPALAN

Date: ______
Joe FENG

Date: ______
Christopher S NGAI

Date: ______
Meiyee (Maggie LE) SHEK

Date: ______
Suketu A PARIKH

Date: ______
Linh H THANH

Attorney Docket No.006398 / DSM/BCVD /JW

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WHEREAS:

Names and Addresses of Inventors:

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1750 Halford Avenue
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______________________ Date: ______________
Nagarajan RAJAGOPALAN

______________________ Date: 7/8/02
Joe FENG

______________________ Date: ______________
Christopher S NGAI

______________________ Date: ______________
Meiyee (Maggie LE) SHEK

______________________ Date: ______________
Suketu A PARIKH

______________________ Date: ______________
Linh H THANH

Attorney Docket No.006398 / DSM/BCVD /JW

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______________________ Date: ____________
Nagarajan RAJAGOPALAN

______________________ Date: ____________
Joe FENG

______________________ Date: July 8, 2002
Christopher S NGAI

______________________ Date: ____________
Meiyee (Maggie LE) SHEK

______________________ Date: ____________
Suketu A PARIKH

______________________ Date: ____________
Linh H THANH

Attorney Docket No.006398 / DSM/BCVD /JW

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

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Joe FENG

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Christopher S NGAI

______________________ Date: 7/8/02
Meiyee (Maggie LE) SHEK

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Linh H THANH

Attorney Docket No.006398 / DSM/BCVD /JW

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Nagarajan RAJAGOPALAN

____________________ Date: __________
Joe FENG

____________________ Date: __________
Christopher S NGAI

____________________ Date: __________
Meiyee (Maggie LE) SHEK

Suketu Parikh Date: 7/2/02
Suketu A PARIKH

____________________ Date: __________
Linh H THANH

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________________________ Date: ____________
Christopher S NGAI

________________________ Date: ____________
Meiyee (Maggie LE) SHEK

________________________ Date: ____________
Suketu A PARIKH

LinhThanh Date: Jul 3, 2002
Linh H THANH